

**256Kx1 Static RAM**

**Features**

- **High speed**
  - 25 ns
- **CMOS for optimum speed/power**
- **Low active power**
  - 880 mW
- **Low standby power**
  - 220 mW
- **TTL-compatible inputs and outputs**
- **Automatic power-down when deselected**

**Functional Description**

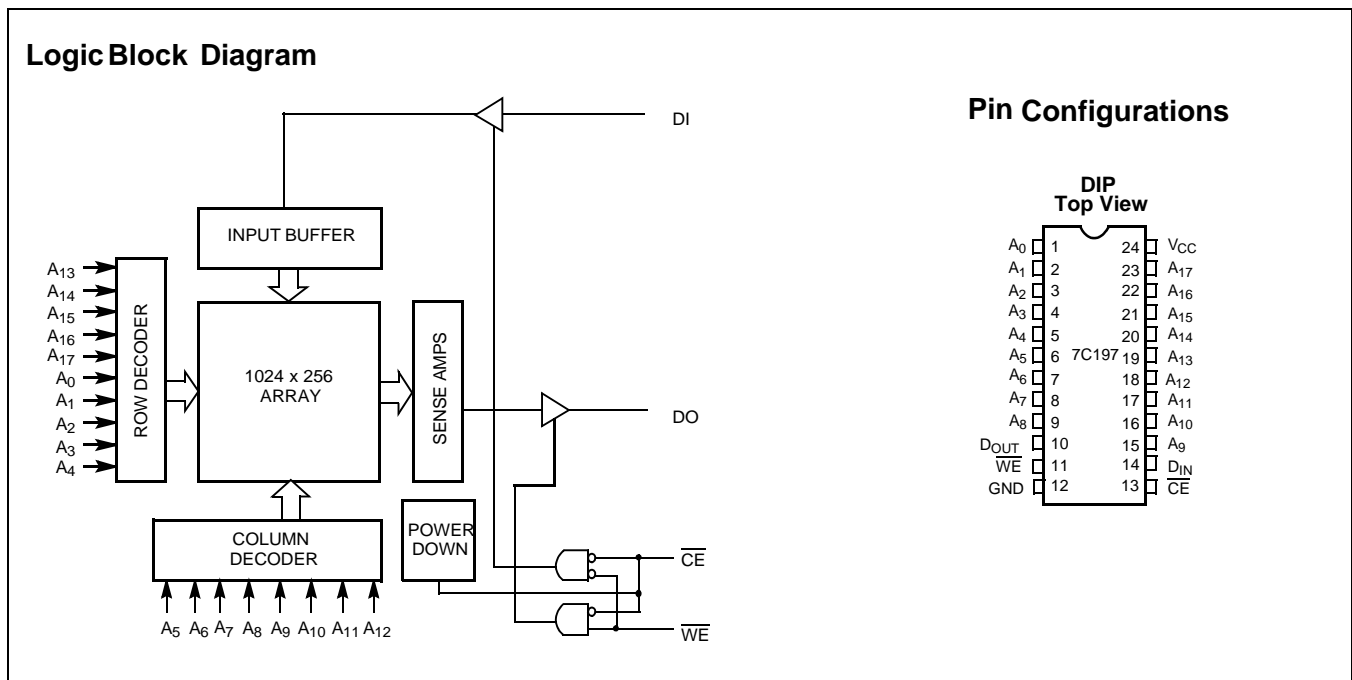
The CY7C197N is a high-performance CMOS static RAM organized as 256K words by 1 bit. Easy memory expansion is provided by an active LOW Chip Enable ( $\overline{CE}$ ) and three-state drivers. The CY7C197N has an automatic power-down feature, reducing the power consumption by 75% when deselected.

Writing to the device is accomplished when the Chip Enable ( $\overline{CE}$ ) and Write Enable ( $\overline{WE}$ ) inputs are both LOW. Data on the input pin ( $D_{IN}$ ) is written into the memory location specified on the address pins ( $A_0$  through  $A_{17}$ ).

Reading the device is accomplished by taking chip enable ( $\overline{CE}$ ) LOW while Write Enable ( $\overline{WE}$ ) remains HIGH. Under these conditions the contents of the memory location specified on the address pins will appear on the data output ( $D_{OUT}$ ) pin.

The output pin stays in a high-impedance state when Chip Enable ( $\overline{CE}$ ) is HIGH or Write Enable ( $\overline{WE}$ ) is LOW.

The CY7C197N utilizes a die coat to insure alpha immunity.



**Selection Guide**

	<b>-25</b>	<b>-45</b>
Maximum Access Time (ns)	25	45
Maximum Operating Current (mA)	95	
Maximum Standby Current (mA)	30	30

**Maximum Ratings**

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature ..... -65°C to +150°C  
 Ambient Temperature with Power Applied..... -55°C to +125°C  
 Supply Voltage to Ground Potential (Pin 24 to Pin 12) ..... -0.5V to +7.0V  
 DC Voltage Applied to Outputs in High Z State<sup>[1]</sup> ..... -0.5V to  $V_{CC} + 0.5V$

DC Input Voltage<sup>[1]</sup> ..... -0.5V to  $V_{CC} + 0.5V$   
 Output Current into Outputs (LOW)..... 20 mA  
 Static Discharge Voltage..... >2001V (per MIL-STD-883, Method 3015)  
 Latch-Up Current..... >200 mA

**Operating Range**

Range	Ambient Temperature	$V_{CC}$
Commercial	0°C to +70°C	5V ± 10%

**Electrical Characteristics** Over the Operating Range

Parameter	Description	Test Conditions	-25, -45		Unit
			Min.	Max.	
$V_{OH}$	Output HIGH Voltage	$V_{CC} = \text{Min.}, I_{OH} = -4.0 \text{ mA}$	2.4		V
$V_{OL}$	Output LOW Voltage	$V_{CC} = \text{Min.}, I_{OL} = 12.0 \text{ mA}$		0.4	V
$V_{IH}$	Input HIGH Voltage		2.2	$V_{CC} + 0.3V$	V
$V_{IL}$	Input LOW Voltage <sup>[1]</sup>		-0.5	0.8	V
$I_{IX}$	Input Load Current	$GND \leq V_I \leq V_{CC}$	-5	+5	mA
$I_{OZ}$	Output Leakage Current	$GND \leq V_O \leq V_{CC}$ , Output Disabled	-5	+5	mA
$I_{OS}$	Output Short Circuit Current <sup>[2]</sup>	$V_{CC} = \text{Max.}, V_{OUT} = GND$		-300	mA
$I_{CC}$	$V_{CC}$ Operating Supply Current	$V_{CC} = \text{Max.}, I_{OUT} = 0 \text{ mA}, f = f_{MAX} = 1/t_{RC}$		95	mA
$I_{SB1}$	Automatic $\overline{CE}$ Power-Down Current—TTL Inputs <sup>[3]</sup>	Max. $V_{CC}$ , $\overline{CE} \geq V_{IH}$ , $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$ , $f = f_{MAX}$		30	mA
$I_{SB2}$	Automatic $\overline{CE}$ Power-Down Current—CMOS Inputs <sup>[3]</sup>	Max. $V_{CC}$ , $\overline{CE} \geq V_{CC} - 0.3V$ , $V_{IN} \geq V_{CC} - 0.3V$ or $V_{IN} < 0.3V$		15	mA

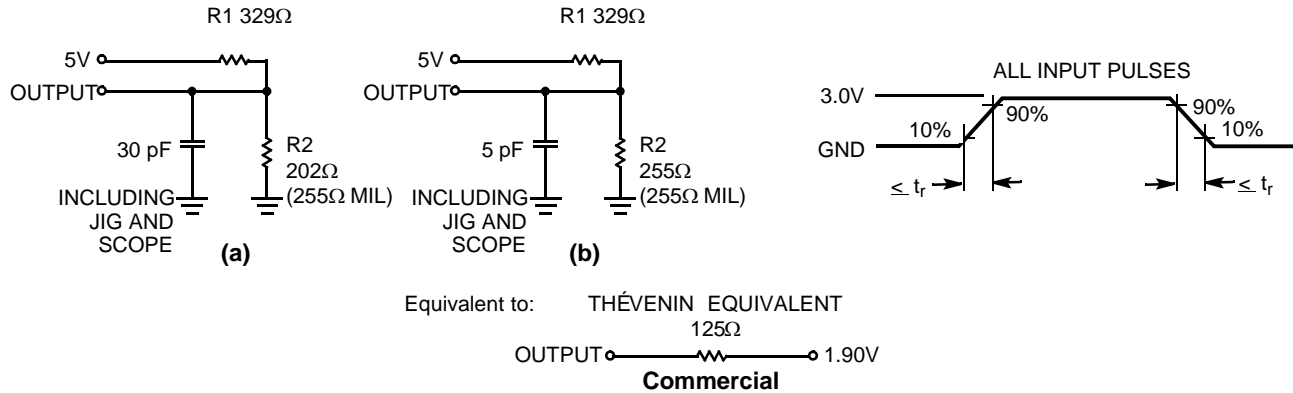
**Capacitance<sup>[4]</sup>**

Parameter	Description	Test Conditions	Max.	Unit
$C_{IN}$	Input Capacitance	$T_A = 25^\circ\text{C}, f = 1 \text{ MHz}, V_{CC} = 5.0V$	8	pF
$C_{OUT}$	Output Capacitance		10	pF

**Note:**

- $V_{(min.)} = -2.0V$  for pulse durations of less than 20 ns.
- Not more than one output should be shorted at one time. Duration of the short circuit should not exceed 30 seconds.
- A pull-up resistor to  $V_{CC}$  on the  $\overline{CE}$  input is required to keep the device deselected during  $V_{CC}$  power-up, otherwise  $I_{SB}$  will exceed values given.
- Tested initially and after any design or process changes that may affect these parameters.
- $t_r = \leq 5 \text{ ns}$  for the -25 and slower speeds.

AC Test Loads and Waveforms<sup>[5]</sup>



Switching Characteristics Over the Operating Range<sup>[8]</sup>

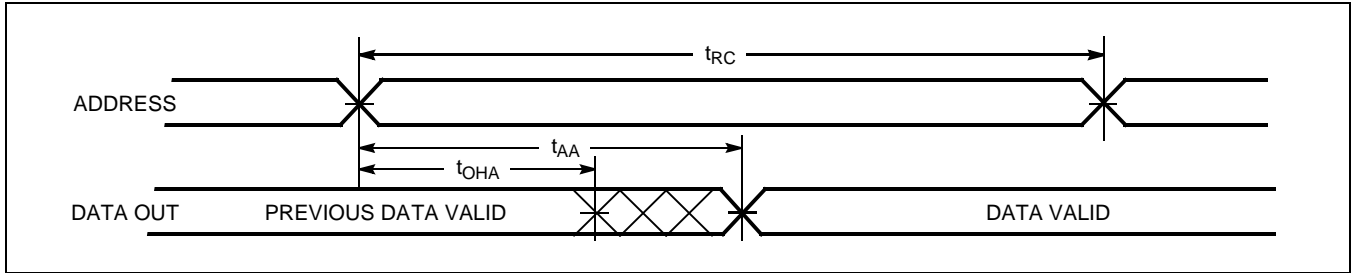
Parameter	Description	-25		-45		Unit
		Min.	Max.	Min.	Max.	
<b>READ CYCLE</b>						
t <sub>RC</sub>	Read Cycle Time	25		45		ns
t <sub>AA</sub>	Address to Data Valid		25		45	ns
t <sub>OHA</sub>	Output Hold from Address Change	3		3		ns
t <sub>ACE</sub>	$\overline{CE}$ LOW to Data Valid		25		45	ns
t <sub>LZCE</sub>	$\overline{CE}$ LOW to Low Z <sup>[9]</sup>	3		3		ns
t <sub>HZCE</sub>	$\overline{CE}$ HIGH to High Z <sup>[9, 10]</sup>	0	11	0	15	ns
t <sub>PU</sub>	$\overline{CE}$ LOW to Power-Up	0		0		ns
t <sub>PD</sub>	$\overline{CE}$ HIGH to Power-Down		20		30	ns
<b>WRITE CYCLE<sup>[11]</sup></b>						
t <sub>WC</sub>	Write Cycle Time	25		45		ns
t <sub>SCE</sub>	$\overline{CE}$ LOW to Write End	20		40		ns
t <sub>AW</sub>	Address Set-Up to Write End	20		40		ns
t <sub>HA</sub>	Address Hold from Write End	0		0		ns
t <sub>SA</sub>	Address Set-Up to Write Start	0		0		ns
t <sub>PWE</sub>	$\overline{WE}$ Pulse Width	20		30		ns
t <sub>SD</sub>	Data Set-Up to Write End	15		20		ns
t <sub>HD</sub>	Data Hold from Write End	0		0		ns
t <sub>LZWE</sub>	$\overline{WE}$ HIGH to Low Z <sup>[9]</sup>	3		3		ns
t <sub>HZWE</sub>	$\overline{WE}$ LOW to High Z <sup>[9, 10]</sup>	0	11	0	15	ns

Note:

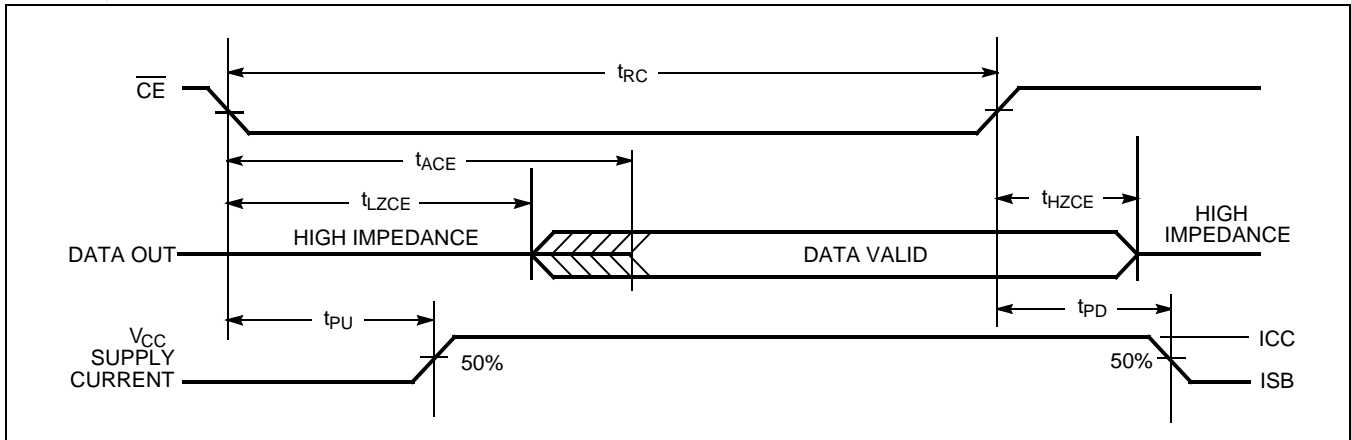
6. Tested initially and after any design or process changes that may affect these parameters.
7. t<sub>r</sub> = ≤ 5 ns for the -25 and slower speeds.
8. Test conditions assume signal transition time of 5 ns or less for -25 and slower speeds, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I<sub>OL</sub>/I<sub>OH</sub> and 30-pF load capacitance.
9. At any given temperature and voltage condition, t<sub>HZCE</sub> is less than t<sub>LZCE</sub> and t<sub>HZWE</sub> is less than t<sub>LZWE</sub> for any given device.
10. t<sub>HZCE</sub> and t<sub>HZWE</sub> are specified with C<sub>L</sub> = 5 pF as in part (b) in AC Test Loads and Waveforms. Transition is measured ±500 mV from steady-state voltage.
11. The internal write time of the memory is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{WE}$  LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.

Switching Waveforms

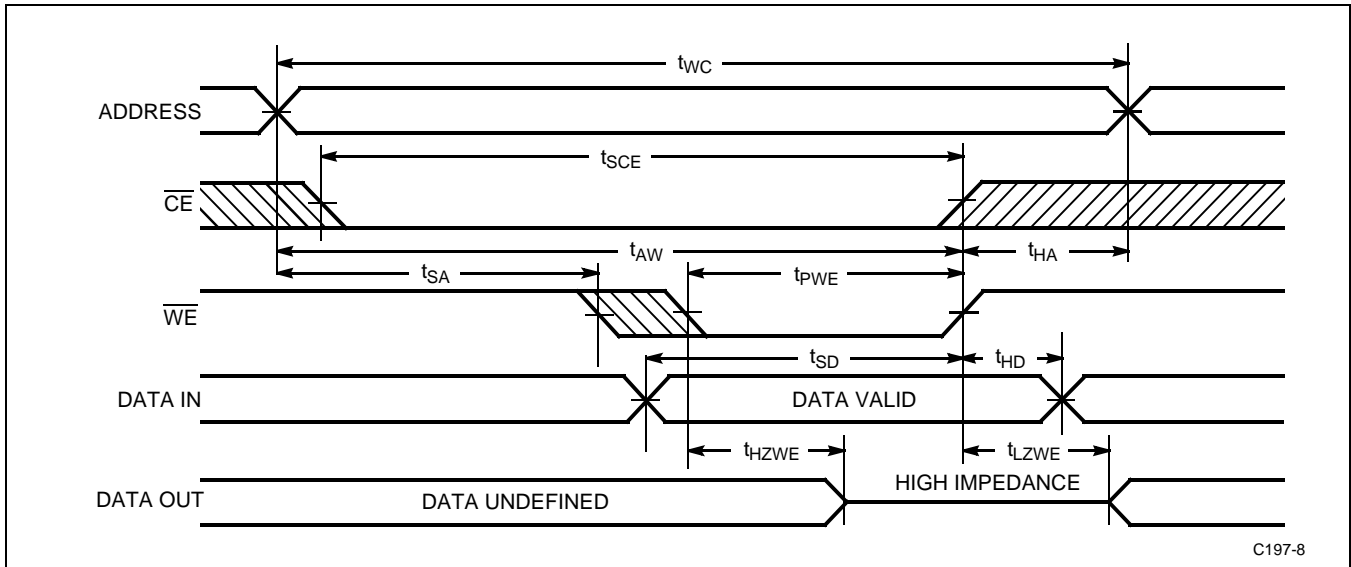
Read Cycle No. 1<sup>[12, 13]</sup>



Read Cycle No. 2<sup>[12]</sup>



Write Cycle No. 1 (WE Controlled)<sup>[11]</sup>



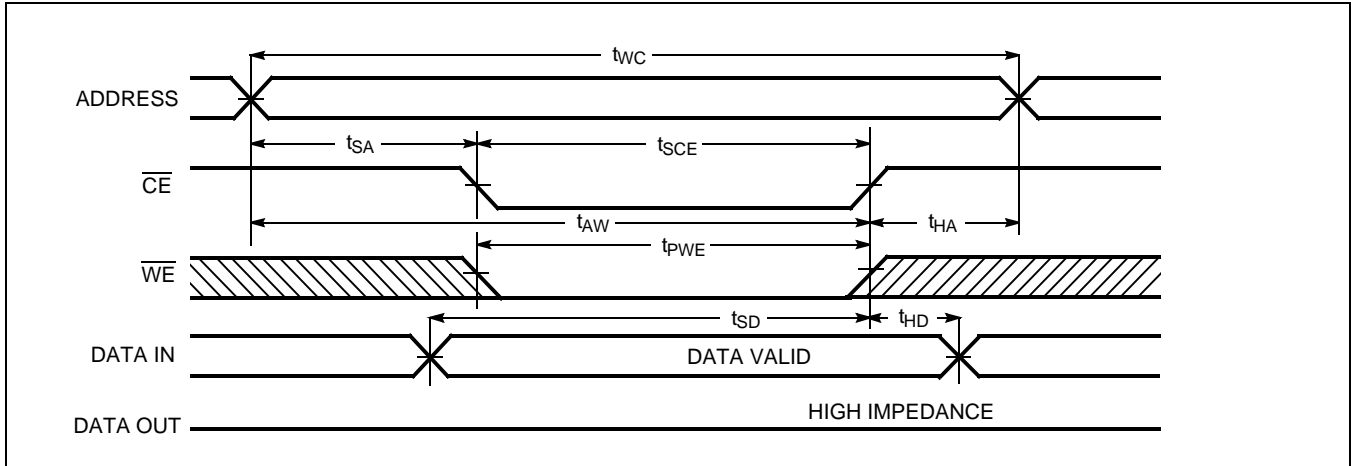
C197-8

Notes:

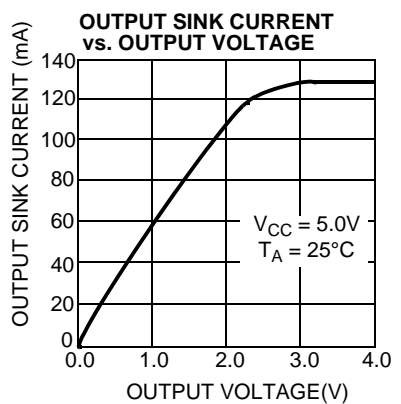
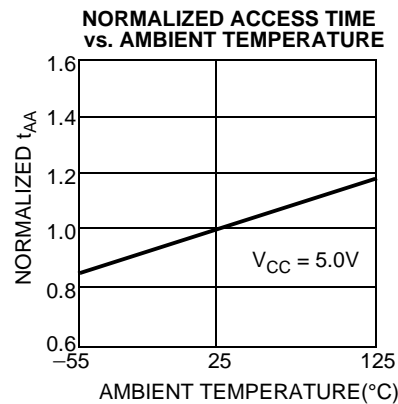
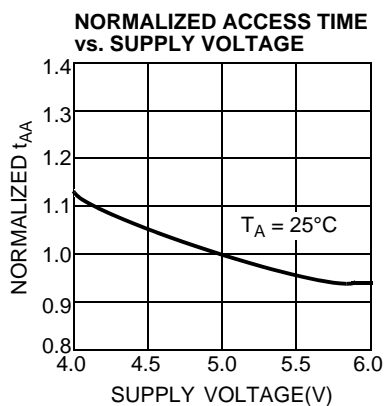
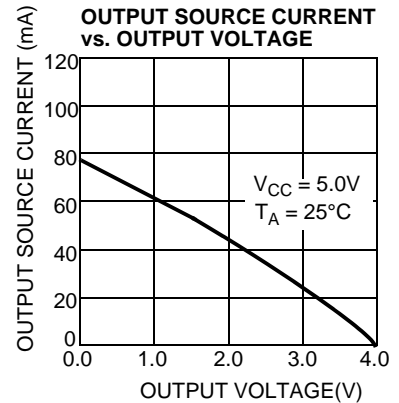
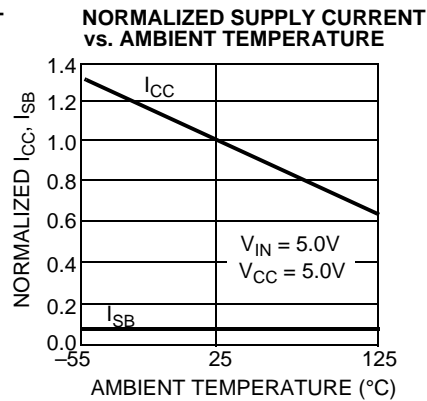
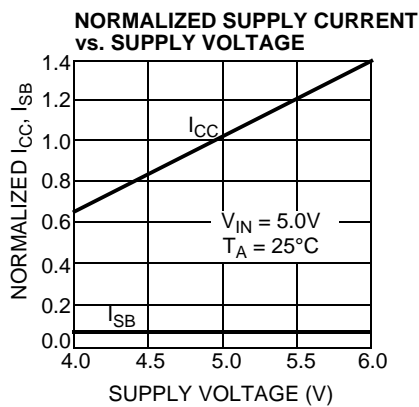
- 12. WE is HIGH for read cycle.
- 13. Device is continuously selected,  $\overline{CE} = V_{II}$ .
- 14. If CE goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.

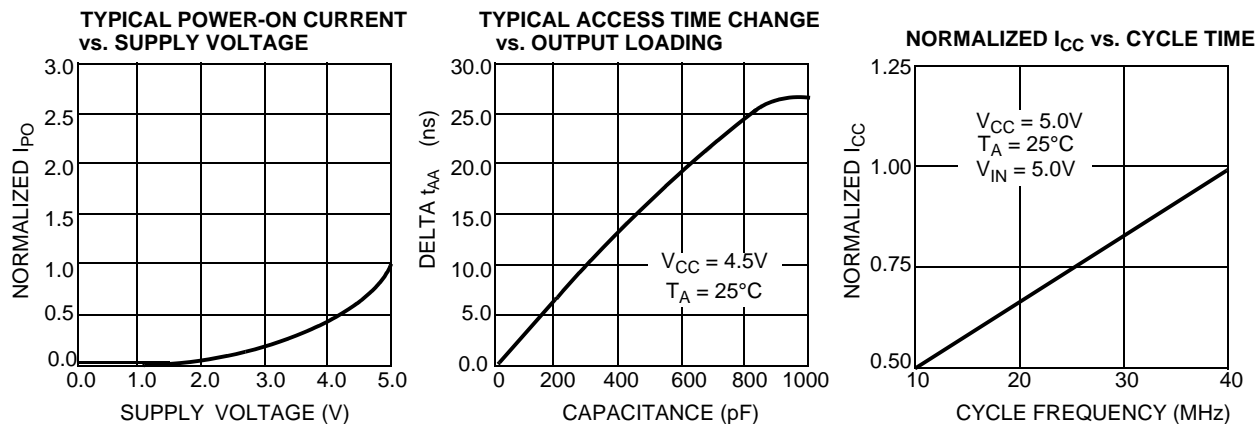
Switching Waveforms (continued)

Write Cycle No. 2 ( $\overline{CE}$  Controlled)<sup>[11, 14]</sup>



Typical DC and AC Characteristics



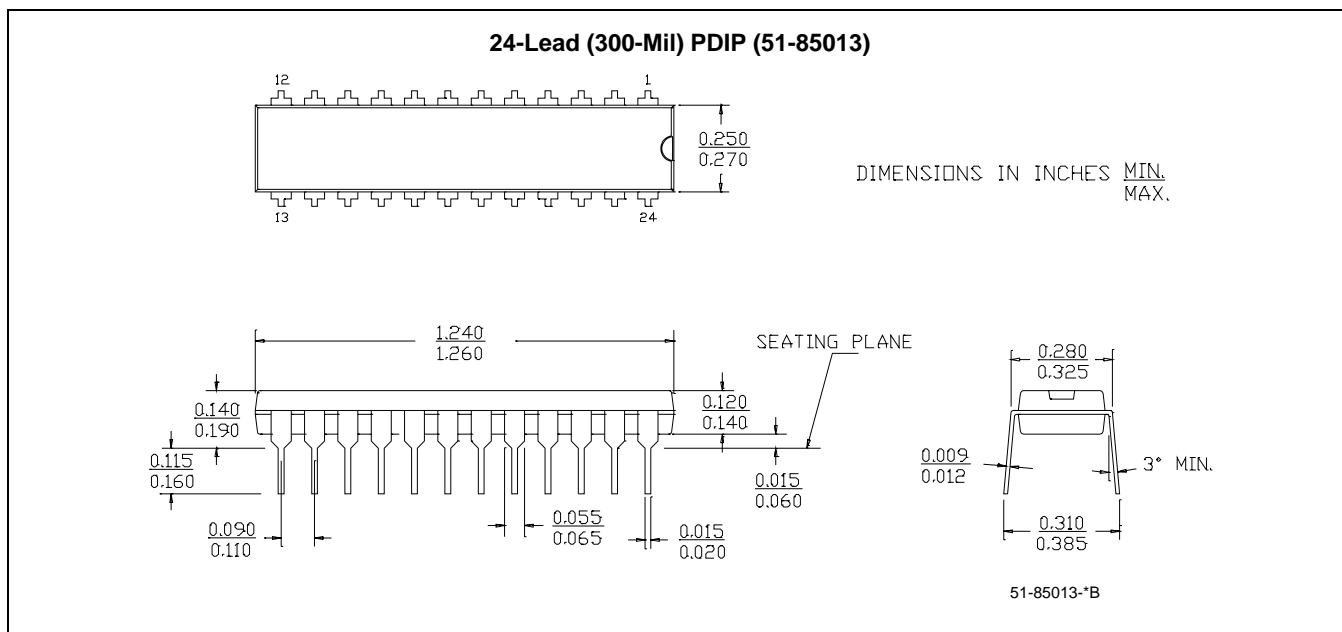
**Typical DC and AC Characteristics** (continued)

**CY7C197N Truth Table**

$\overline{CE}$	$\overline{WE}$	Input/Output	Mode
H	X	High Z	Deselect/Power-Down
L	H	Data Out	Read
L	L	Data In	Write

**Ordering Information**

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
25	CY7C197N-25PXC	51-85013	24-Lead (300-Mil) Molded DIP (Pb-free)	Commercial
45	CY7C197N-45PXC	51-85013	24-Lead (300-Mil) Molded DIP (Pb-free)	Commercial

Please contact local sales representative regarding availability of these parts.

**Package Diagram**


All products and company names mentioned in this document may be the trademarks of their respective holders.

**Document History Page**

<b>Document Title: CY7C197N 256Kx1 Static RAM</b> <b>Document Number: 001-06495</b>				
<b>REV.</b>	<b>ECN NO.</b>	<b>Issue Date</b>	<b>Orig. of Change</b>	<b>Description of Change</b>
**	424111	See ECN	NXR	New Data Sheet